A.L.S. Technology Infobion Sputtering System Catalog

We can supply the HQ sputtering system at a reasonable price.

ALS
Vaccum is our business
株式会社 エイエルエステクノロジー

Co-operate with

DISPLAY & PLASMA TECHNOLOGY
iNFOVION
INFOVION Inc.

Ion Beam Sputtering System
Combinatorial
Specification

In addition to our conventional composite sputtering systems, we have decided to strengthen our dedicated sputtering equipment business. We are collaborating with Infovion, based in Seoul, South Korea, to market and sell their excellent sputtering equipment in the Japanese market.

About Infovion

(1) Introduction to Infovion

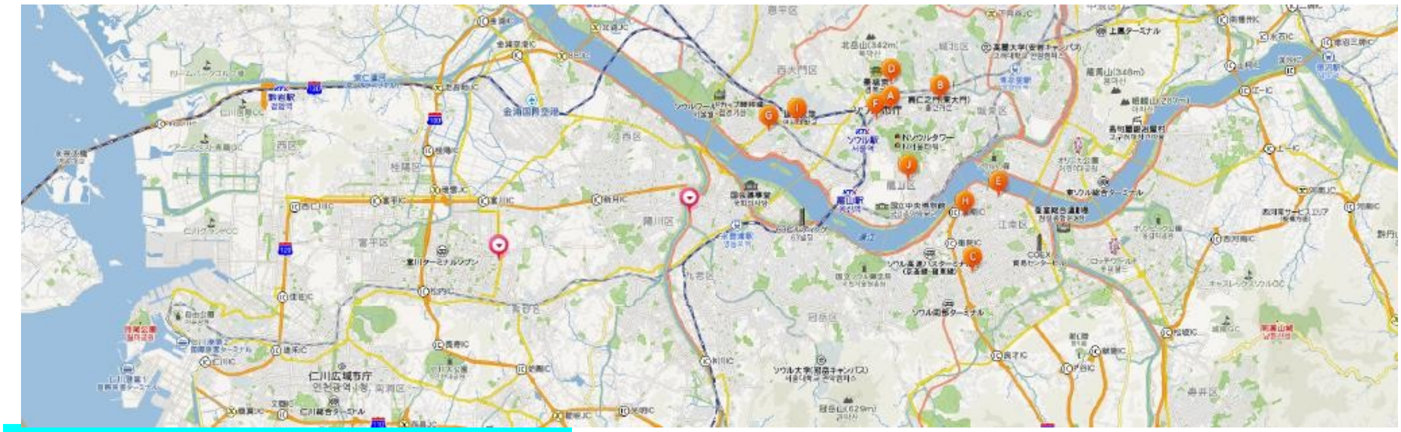
Infobion Co., Ltd. is a Korean vacuum equipment manufacturer offering a wide range of products, from compact devices for university research to large inline systems and cluster systems.

- Product Examples Ion guns, EB assist guns, large carousel batch spitters, inline film deposition equipment, cluster film deposition equipment, ALD equipment, and more.
- Areas of expertise We possess a high level of unique technology for handling ions and electrons.

(2) Location

A ddress: 5-3, Mullae-dong 5-ga, Yeongdeungpo-gu, Seoul 150-095, Korea http://www.infovion.com

Located within 5 km of Yeouido (the area housing the National Assembly building), the political and economic center in central Seoul, Korea.(Within 30 minutes by car from Gimpo International Airport, within 30 minutes by subway from Seoul Station to the nearest station)



Installation, adjustment, delivery, etc.

- Customer witness inspections are possible at our factory (Japan).

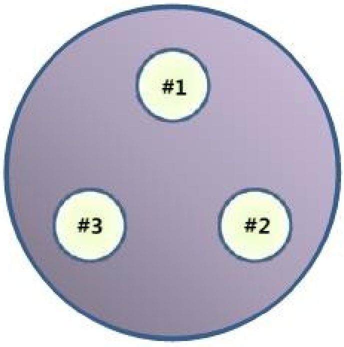
  We generally request witnessing at Infobion's factory (Seoul).
- Our Japanese technicians will travel to your site for installation, adjustment, and handover.

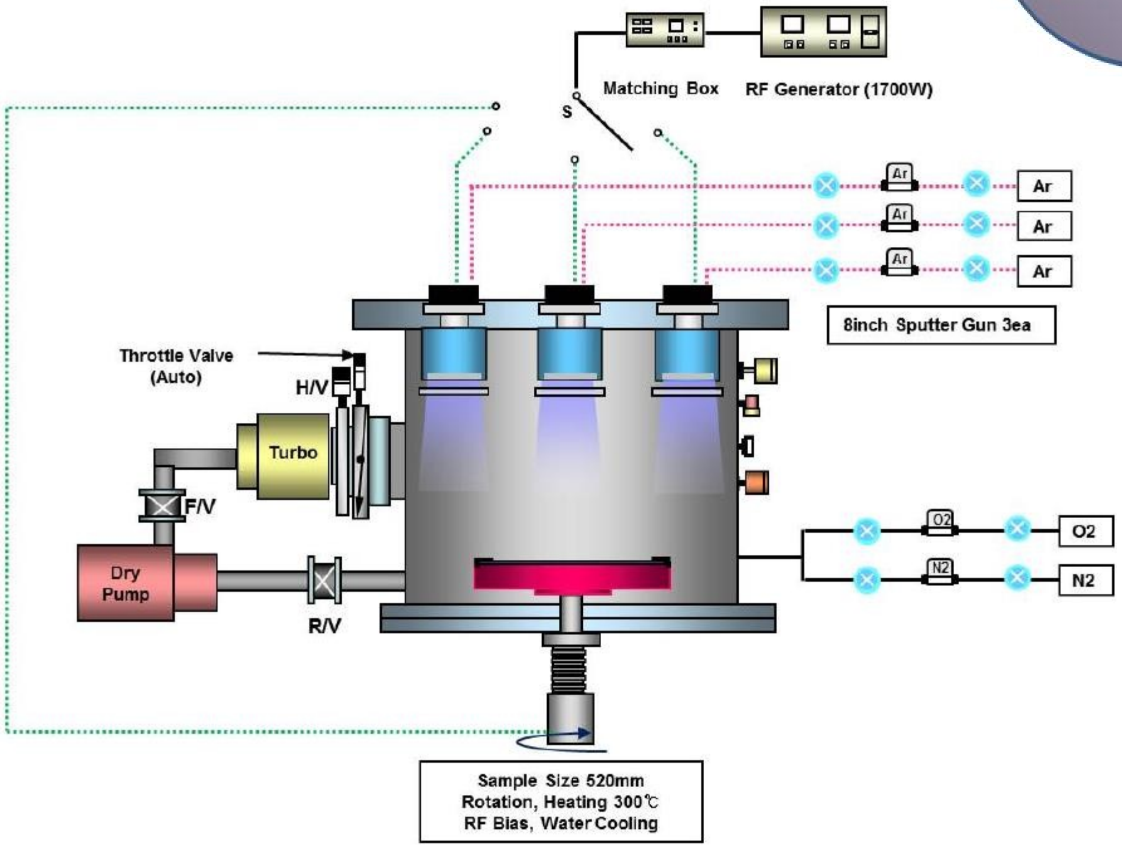
Warranty and After-Sales Service

(1) Quality Warranty One-year free warranty period

(2) After the free warranty period ends, our company's (Japan) engineers will take responsibility for repairs and other services.

Model Number	**S-ISM-1830**
Classification	Parallel Plate Sputtering System (Φ8-inch cathode x , 3 units)
Application	Small-scale production and research



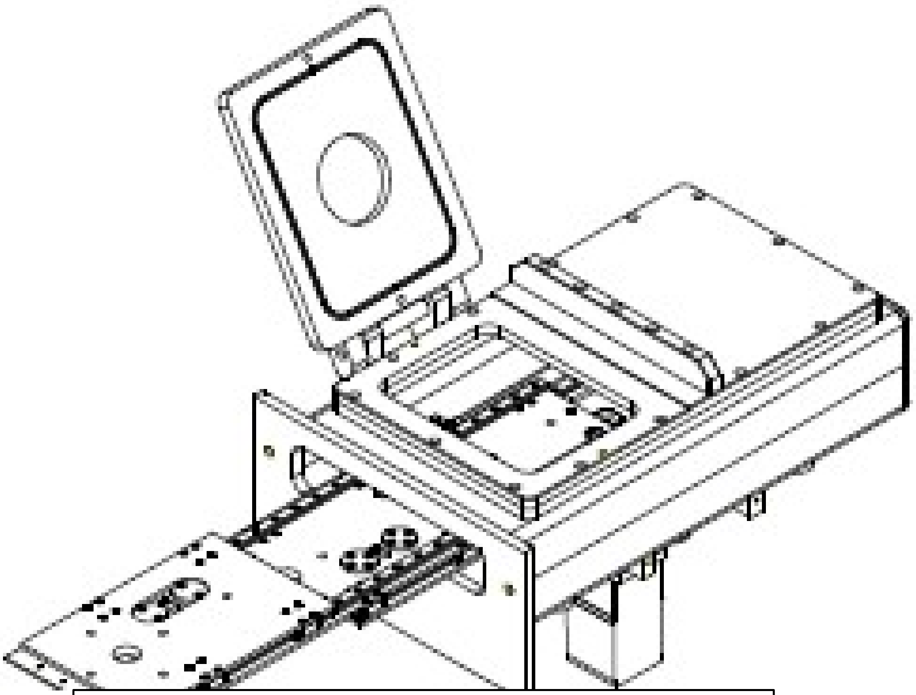


Main Specifications

	Main Components	Specifications
Sputtering Chamber	Multi-Cathode	8-inch planar magnetron cathodes x 3 units
	Sputter Power Supply	RF, 13.56 MHz, 1700W x 1 unit, Cathode Switch
	Matching	Auto-matching x 1 unit
	Shutter	Individual Shutter x 3 units
	Board Holder	Holder Diameter Φ520 mm
		Water-cooled, substrate heating (300°C, PID control)
		Substrate rotation 5 rpm Magnetic fluid seal
	Reverse Sputtering	Options
	Film deposition performance	±10% within Φ400 mm
Exhaust System	Main Exhaust Pump	Turbo Molecular Pump 2,400 L/sec (N_2)
	Roughing Pump	Dry Pump
	Sputter Pressure Control	Throttle valve / Automatic pressure adjustment mechanism
	Vacuum Performance	10^{-7} Torr range
Gas Introduction	Gas Type	Ar (100 sccm) (O_2, N_2, etc.)
	Control Valve	Mass Flow Controller
Control System	Large Screen Display	Keyboard Input
	Film Deposition Operation	Fully automated by recipe
	Exhaust Operation	Automatic

Options

- Load Lock System
- Sputtering Power Supply (RF/DC)
- Process Gas Types and Flow Rates
- Other requirements will be accommodated upon customer request.



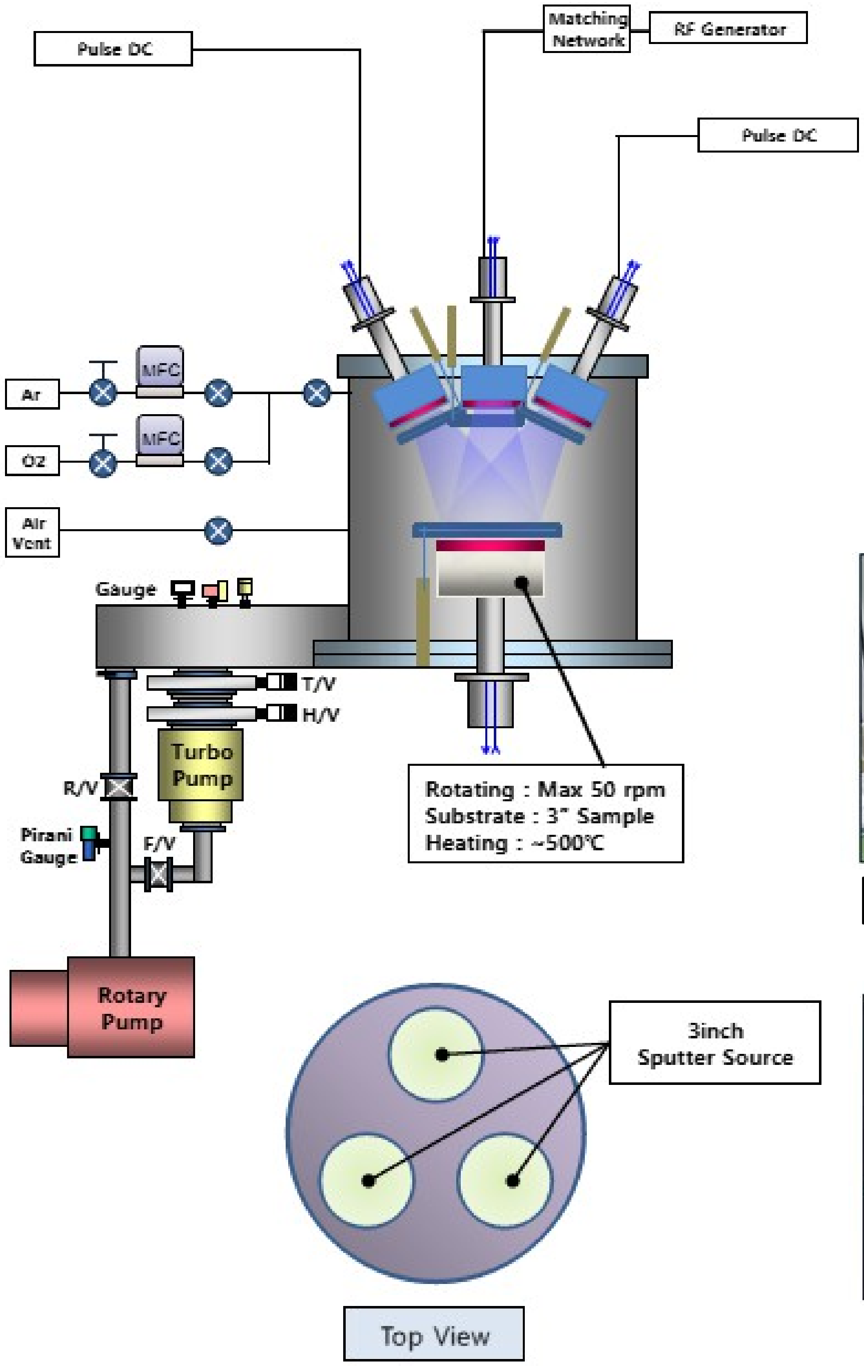
Load Lock System

Model Number	**S-IS-1330**
Classification	Sputtering System (3 x 3-inch cathodes, Focusing configuration)
Application	Research (semiconductor, new material development, sensor development, etc.)

Features Automatic film deposition based on recipes is possible.

Simultaneous discharge from three cathodes possible

Capable of layered films and mixed films (with composition control) Compact design



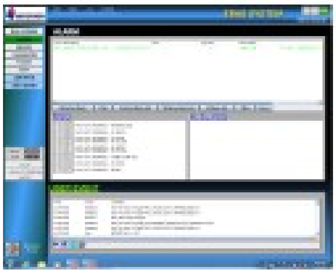
Φ3-inch cathode (diagonal arrangement)

Substrate holder compatible with Φ3-inch substrates

Main Specifications

	Main Components	Specifications
Sputtering Chamber	Multi-Cathode	3-inch planar magnetron cathodes x 3 units (Focusing configuration)
	Sputter Power Supply	RF, 13.56 MHz, 600W x 1 unit, Pulse DC x 2 units
	Matching	Auto-matching x 1 unit
	Shutter	Individual Shutters (3 Cathode Shutters, 1 Substrate Shutter)
	Substrate Holder	Sample Holder Diameter Φ3 inches
		Water-cooled, substrate heating (500°C, PID control)
		Substrate rotation 50 rpm Magnetic fluid seal
	Reverse sputtering	Options
	Film Deposition Performance	±10% at Φ3 inches
Exhaust System	Main Pump	Turbo Molecular Pump 1,100 L/sec (N_2)
	Roughing Pump	Rotary Pump
	Sputter Pressure Control	Throttle valve / Automatic pressure adjustment mechanism
	Vacuum Performance	10^{-7} Torr range
Gas Introduction	Gas Type	Ar: 50 sccm /O_2: 20 sccm
	Control Valve	Mass Flow Controller
Control System	Large Screen Display	Keyboard Input
	Film Deposition Operation	Fully automated by recipe
	Exhaust Operation	Automatic

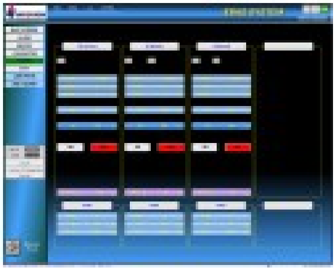
Alarm



Parameter

Recipe

History



Examples of Other Equipment

(The catalog devices listed above are just a few examples. Please contact us for details.)

INFOVION's Multi Layer

E-beam Evaporator System

INFOVION's E-beam Evaporator System is Highly Reliable for Wide Range of Production and Research Applications

INFOVION's Ion Beam Sputter

Deposition System

INFOVION's IBSD System has Unique Characteristics, Including Process Optimization & Versatility that is Suitable for Difficult Applications

INFOVION's

COMBI-Sputter

INFOVION's Combinatorial Sputter System can dramatically accelerate the discovery of ideal compound and optimization process.